

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
8	BRS	L8	1753704	inductor or semiconductor or IC or (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2003/08/29 15:07	
9	BRS	L9	26331	8 and passive and active	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2003/08/29 15:12	
10	BRS	L11	1262	9 and ((crib\$4 or cut\$6 or dic\$6) with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2003/08/29 15:10	
12	BRS	L13	235	9 and (((crib\$4 or cut\$6 or dic\$6 or remove) with substrate) same (pad or bondpad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2003/08/29 15:11	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	L1	23425	inductor and (semiconductor or IC or (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2003/08/29 14:34	
3	BRS	L3	3070	1 and (glass or glass-panel)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2003/08/29 14:34	
5	BRS	L5	1639	3 and (crib\$4 or cut\$6 or dic\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2003/08/29 14:36	
6	BRS	L6	470	5 and passive and active	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2003/08/29 14:36	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
7	BRS	L7	262	6 and (pad or bondpad)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2003/08/2 9 14:36	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
5	BRS	L5	483	planar adj induct\$4	USPAT; US-P GPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/29 11:44	
6	BRS	L6	118	5 and (scrib\$4 or cut\$6)	USPAT; US-P GPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/29 11:44	
7	BRS	L7	27	6 and (pad or bondpad)	USPAT; US-P GPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/29 11:45	